

L Number	Hits	Search Text	DB	Time stamp
-	59	(mesh near2 (infiltrate or infiltrating or infiltrated or infiltration) near2 mesh)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:34
-	1	(solder near2 mesh near2 (infiltrate or infiltrating or infiltrated or infiltration) near2 mesh)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:34
-	2	(solder near2 mesh near2 (infiltrate or infiltrating or infiltrated or infiltration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:35
-	5	(solder near2 mesh near2 (filled or infiltrate or infiltrating or infiltrated or infiltration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:38
-	18	(solder near5 mesh near5 (filled or infiltrate or infiltrating or infiltrated or infiltration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:40
-	179	(solder near5 (woven or wire or mesh) near5 (filled or infiltrate or infiltrating or infiltrated or infiltration))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:41
-	48	(solder near5 (woven or wire or mesh) near5 (filled or infiltrate or infiltrating or infiltrated or infiltration)) and (pcb or (printed near circuit near board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:41
-	6	(solder near5 (woven or wire or mesh) near5 (filled or infiltrate or infiltrating or infiltrated or infiltration)).ti,ab,clm. and (pcb or (printed near circuit near board)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 10:42
-	14	(solder near5 (woven or wire or mesh) near5 (filled or infiltrate or infiltrating or infiltrated or infiltration)) and (pcb or (printed near circuit near board)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/08/03 13:11

L Number	Hits	Search Text	DB	Time stamp
-	199149	(bond or bonding or bonded) and joint and mesh solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:21
-	917	(bond or bonding or bonded) and joint and mesh and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:21
-	137	(bond or bonding or bonded) and joint and mesh.clm. and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:22
-	63	(bond or bonding or bonded).clm. and joint and mesh.clm. and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:22
-	16	(bond or bonding or bonded).clm. and joint.clm. and mesh.clm. and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:22
-	7	(bond or bonding or bonded).clm. and joint.clm. and mesh.clm. and solder.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:23
-	1	((bond or bonding or bonded).clm. and joint.clm. and mesh.clm. and solder.clm.) and (mesh near10 solder near10 (bond or bonding or bonded)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:23
-	1	((bond or bonding or bonded).clm. and joint.clm. and mesh.clm. and solder.clm.) and (mesh near10 solder near10 (bond or bonding or bonded))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:23
-	26	(mesh near10 solder near10 (bond or bonding or bonded))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/30 13:23

L Number	Hits	Search Text	DB	Time stamp
-	5	((meshed or meshing or mesh) near3 (solder or soldering or soldered)).ti,ab,clm. and (bond or bonding or bonded) and (connector or joint or joining or joined or connecting or connected or connection) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 09:59
-	6	((meshed or meshing or mesh) near5 (solder or soldering or soldered)).ti,ab,clm. and (bond or bonding or bonded) and (connector or joint or joining or joined or connecting or connected or connection) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:00
-	23	((meshed or meshing or mesh) near2 (solder or soldering or soldered)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:02
-	4	(mesh near5 (bond or bonding or bonded) near5 (joint or connector)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:02
-	22	mesh near5 (bond or bonding or bonded) near5 (joint or connector)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:03
-	14	(mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected)).ti,ab,clm. and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:05
-	97	(mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:07
-	5	(mesh near2 (bond or bonding or bonded) near2 (joint or connector or joining or joined or connection or connecting or connected)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:07
-	18	(mesh near3 (bond or bonding or bonded) near3 (joint or connector or joining or joined or connection or connecting or connected)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:08
-	30	(mesh near4 (bond or bonding or bonded) near4 (joint or connector or joining or joined or connection or connecting or connected)).ti,ab,clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:08

-	10	(mesh near4 (bond or bonding or bonded) near4 (joint or connector or joining or joined or connection or connecting or connected)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:09
-	13	(mesh near5 (bond or bonding or bonded) near5 (joint or connector or joining or joined or connection or connecting or connected)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:10
-	31	(mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:13
-	283	(mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:13
-	2	((mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))) and (power near semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:14
-	24	((mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))) and (power and semiconductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:45
-	1	((mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))) and (power and semiconductor)) and (mesh near (fill or filling or filled or infiltrate or infiltrating or infiltrated or infiltration or impregnate or impregnating or impregnated or impregnation)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:46
-	2	((mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))) and (power and semiconductor)) and (mesh near (fill or filling or filled or infiltrate or infiltrating or infiltrated or infiltration or impregnate or impregnating or impregnated or impregnation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:46

-	4	(((mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))) and (power and semiconductor)) and (mesh near2 (fill or filling or filled or infiltrate or infiltrating or infiltrated or infiltration or impregnate or impregnating or impregnated or impregnation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:47
-	25	(((mesh near10 (bond or bonding or bonded) near10 (joint or connector or joining or joined or connection or connecting or connected))) and (mesh near2 (fill or filling or filled or infiltrate or infiltrating or infiltrated or infiltration or impregnate or impregnating or impregnated or impregnation))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/10 10:53